

## AMENDMENT OF THE SPECIFICATION

Please amend the paragraph starting on line 15 of page 1 as follows:

B1  
As shown in FIG. 8, a wafer transfer system A' constituting a semiconductor fabricating system (not shown) is designed to take wafers U, one by one, out of a wafer carrier C, which is provided on the top face of a load port unit L, to transfer the wafers U to a wafer processing system E and to transfer the wafers U, which have been processed by the wafer processing system E, to the wafer carrier C again. At this time, if dust adheres to the wafers U, the wafers U ~~are easy to be~~ can be defective. In order to prevent this, a clean air supply system 4 is provided in the upper portion of the wafer transfer system A' for always supplying clean air K from the unit 4 to the wafers U. This clean air K is blown from top to bottom of a wafer transfer robot R constituting the wafer transfer system A'. Dust existing in the wafer transfer system A' is carried toward the bottom by the flow of the clean air K, and exhausted by an exhaust fan 5 which is provided on the bottom portion 1c of a system body 1. Thus, dust is prevented from adhering to the wafers U.

[Please amend the paragraph starting at line 32 of page 1 as follows:]

In a conventional wafer transfer system, a ball screw and a control motor are used for linearly reciprocating a wafer transfer robot. Since the distance of the movement of the wafer transfer robot ~~can not so long~~ is not long in the case of the ball screw, a wafer transfer system for linearly reciprocating the wafer transfer robot by means of a linear motor has been developed.

**Please amend the paragraph starting on line 1 of page 2 as follows:**

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Referring to FIG. 8, a wafer transfer system A' using a linear motor M will be described below. In a case where the linear motor M is used, the secondary side 11 of the motor M is usually mounted on the bottom portion 1c of the system body 1. However, in this case, the portion of the exhaust ~~fun~~ fan 5 is covered with the secondary side 11 of the linear motor M, so that there is a problem in that exhaust efficiency deteriorates. In addition, since the wide area of the secondary side 11 of the linear motor M faces upwards, dust is easy to be deposited on the top face of the secondary side 11, and this dust is sometimes carried by the flow of the clean air K to float. In such a case, dust is easy to adhere to the wafers U, so that the rate of occurrence of defective wafers U rises.

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